

2010

GreenMil International

Quality Team

[PCB COMPONENT CREATION CHECKLIST]

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Date:

New PCB Component Creation Checklist

Component Name:		Type		Board Name:	
Part No.				Created By:	
Make				Verified By	
Sl. No.	Description				
1.	Check the orientation of the component with the datasheet. Ensure that the component is created with the view from Top.				
2.	Check the Dimensions of the created components with the datasheet.				
3.	Check if the Pad drill hole diameters/slots are as per datasheet.				
4.	Check if sufficient pad area is provided for soldering				
5.	For QFN Packages (having thermal Pads) check if Vias have been provided on the thermal pads for connectivity to plane.				
6.	For BGA's check if a 'no component placement' area of 100mils surrounding the BGA is provided on the component side.				
7.	Check if local fiducials have been provided for fine pitch components.				
8.	Check if a placement boundary of 15 – 25 mils more wrt component outline has been provided. (keep out from other components)				
9.	Check if both silkscreen outline and assembly outline have been provided.				
10.	Check if polarity markings have been provided if the component is polarized.				



11.	Check if direction markings have been provided for right angled connectors/switches/components which are to be accessed from outside.	
12.	Check if pin no./names have been provided on the silkscreen and assembly for components having pin count > 2.	
13.	Check if the Pin no./names provided on the silkscreen and assembly are correct.	
14.	Check if thermal pads and anti pads have been provided in the inner layers for through hole components.	
15.	Check if solder mask opening of minimum 5 mils have been provided for all the pads	
16.	Check if solder mask openings have been provided on both the solder and component side for through hole pads.	
17.	Check if solder paste pads equal to the pad size have been provided for all smd pads.	
18.	Check if the dimensions of the components have been marked on the 'dimension' layer (in mils).	
19.	Check if the names of the pads used are entered in the 'pad_stack_name' subclass layer	
20.		

Checked By

Verified By

Date:

Date: